



DA6X108K0R

Silicon epitaxial planar type

For small current rectification
 DA2J108 in Mini6 type package

■ Features

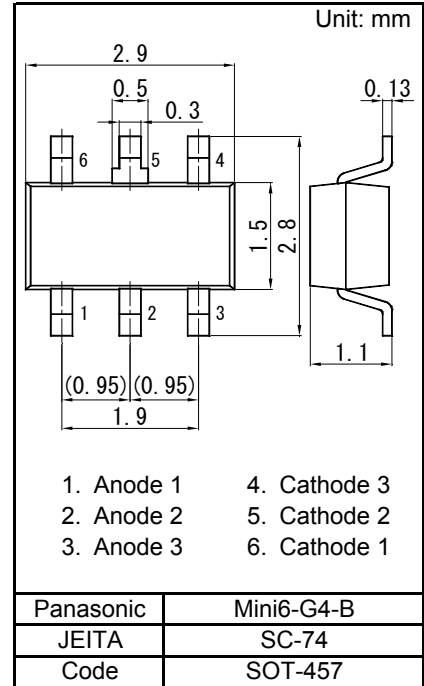
- Small reverse current IR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 26

■ Basic Part Number :
 Triple DA2J108 (Parallel)

■ Packaging

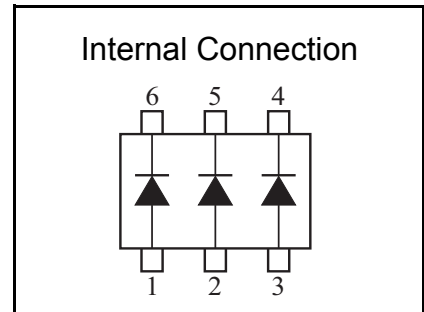
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	300	V
Maximum peak reverse voltage	VRM	300	V
Output current (Average)	Single	200	mA
	Triple	100	
Repetitive peak forward current	Single	600	mA
	Triple	200	
Non-repetitive peak forward surge current *1	Single	1 000	mA
	Triple	350	
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 t = 1 s





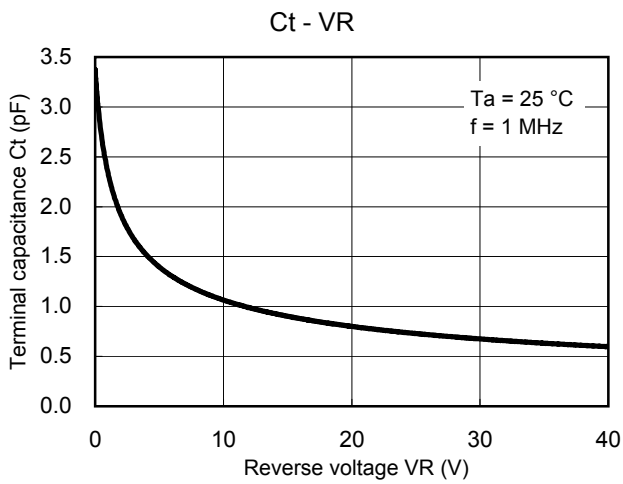
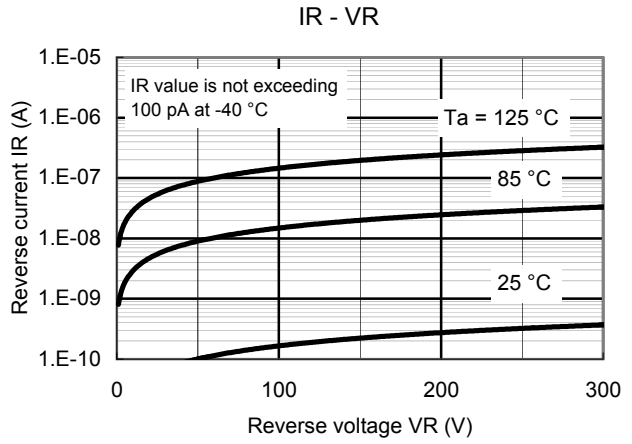
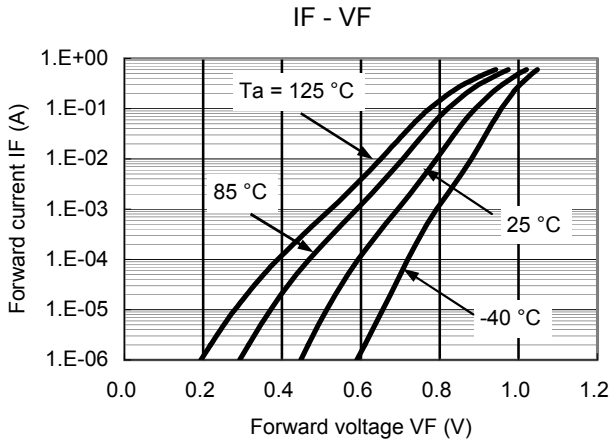
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Reverse current	IR1	VR = 200 V			200	nA
	IR2	VR = 300 V			1	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		3.5		pF

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 3 MHz.



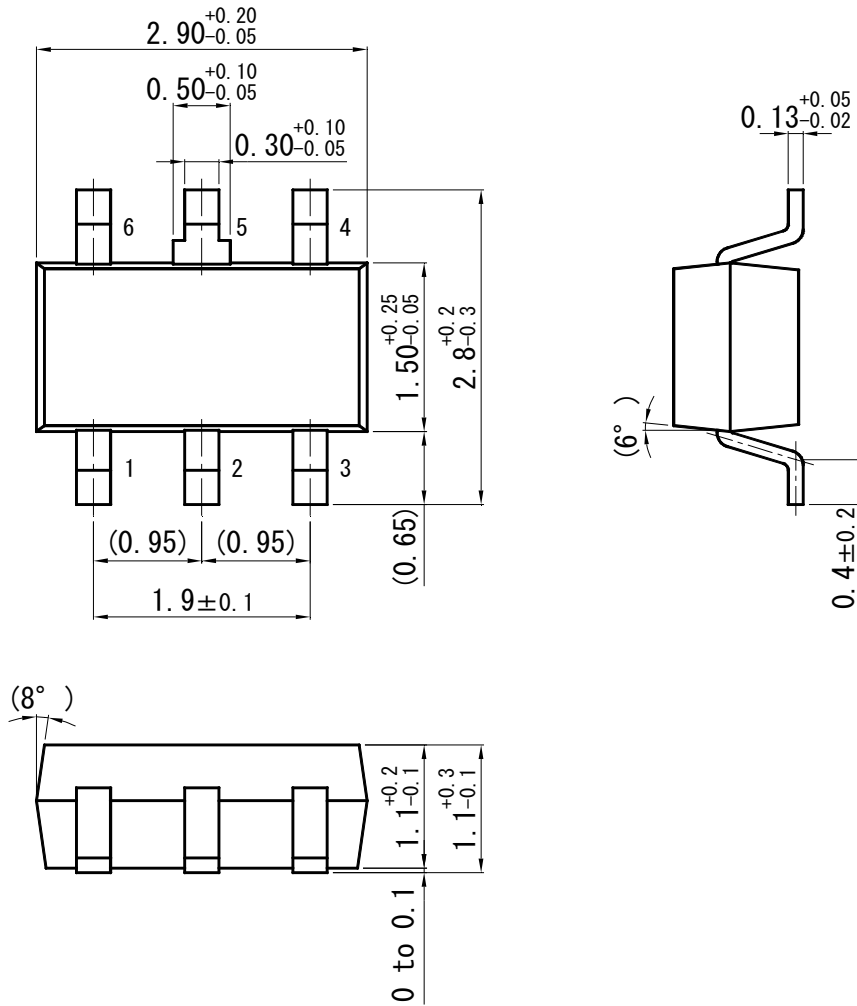
Technical Data (reference)



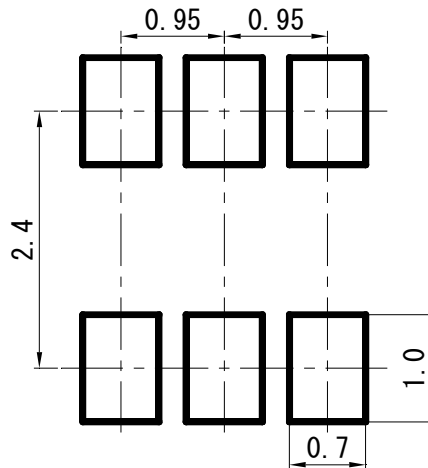


Mini6-G4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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